# PATENT ASSIGNMENT

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| SUBMISSION TYPE: | NEW ASSIGNMENT |
| NATURE OF CONVEYANCE: | ASSIGNMENT |

CONVEYING PARTY DATA

| Name | Execution Date |
|---|---|
| Chin-Tien Chiu | 04/28/2006 |
| Hem Takiar | 04/27/2006 |
| Hui Liu | 04/28/2006 |
| Java Zhu | 04/28/2006 |
| Jack Chang-Chien | 04/28/2006 |
| Cheemen Yu | 04/28/2006 |

RECEIVING PARTY DATA

| | |
|---|---|
| Name: | SanDisk Corporation |
| Street Address: | 140 Caspian Court |
| City: | Sunnyvale |
| State/Country: | CALIFORNIA |
| Postal Code: | 94089 |

PROPERTY NUMBERS Total: 1

| Property Type | Number |
|---|---|
| Application Number: | 11414780 |

CH $40.00 11414780

CORRESPONDENCE DATA

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|---|---|
| ATTORNEY DOCKET NUMBER: | SAND-01107US1 |
| NAME OF SUBMITTER: | Brian I. Marcus |

Total Attachments: 7
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# JOINT TO CORPORATE ASSIGNMENT

WHEREAS, the undersigned Inventors:
(1) Chin-Tien Chiu, a resident of 10F-13, No. 1, Lane 58, Gongye 1st Rd., Situn District #407, Taichung City, Taiwan, R.O.C.;

(2) Hem Takiar, a resident of 1544 Blackfoot Drive, Fremont, California 94539, U.S.A.;

(3) Hui Liu, a resident of No. 899, Yinggang Road, Room 403, No. 175, Ying Hu San Dao, OingPu District, Shanghai, China;

(4) Java Zhu, a resident of Room 601, No. 42, Lane 112, Mistopu Road, Pudong, Shanghai, China 200135;

(5) Jack Chang-Chien, a resident of 9F No.56 Ching-Feng St., Ku-Shan Dist., Kaoshiung City 804, Taiwan, R.O.C.; and

(6) Cheemen Yu, a resident of 2 Dunraven Court, Madison, Wisconsin 53705, U.S.A.,

have invented certain new and useful improvements in:

METHOD OF REDUCING MECHANICAL STRESS ON
A SEMICONDUCTOR DIE DURING FABRICATION

and have executed a declaration for an application for a United States Patent disclosing and identifying the invention, said application having Application Number 11/414,780 and filed on the 28th day April, 2006.

WHEREAS SanDisk Corporation (hereinafter termed "Assignee"), a corporation of the State of Delaware, having a place of business at 140 Caspian Court, Sunnyvale, State of California, wishes to acquire the entire right, title and interest in and to said application and the invention disclosed therein, and in and to all embodiments of the invention, heretofore conceived, made or discovered jointly or severally by said Inventors (all collectively hereinafter termed "said invention"), and in and to any and all patents, certificates of invention and other forms of protection thereon (hereinafter termed "patents") applied for or granted in the United States and/or other countries.

NOW THEREFORE, for good and valuable consideration acknowledged by each of said Inventors to have been received in full from said Assignee:

1. Said Inventors do hereby sell, assign, transfer and convey to said Assignee, the entire right, title and interest (a) in and to said application and said invention; (b) in and to all rights to apply in any or all countries of the world for patents, certificates of inventions or other governmental grants on said invention, including the right to apply for patents pursuant to the International Convention for the Protection of Industrial Property or pursuant to any other convention, treaty, agreement or understanding; (c) in and to any and all applications filed and any and all patents, certificates of inventions or other governmental grants granted on said invention in the United States or any other country, including each and every application filed and each and every patent granted on any application which is a division,

substitution, or continuation of any of said applications; (d) in and to each and every reissue or extension of any of said patents; and (e) in and to each and every patent claim resulting from a reexamination certificate for any and all of said patents.

2. Said Inventors hereby jointly and severally covenant and agree to cooperate with said Assignee to enable said Assignee to enjoy to the fullest extent the right, title and interest herein conveyed in the United States and other countries. Such cooperation by said Inventors shall include prompt production of pertinent facts and documents, giving of testimony, executing of petitions, oaths, specifications, declarations or other papers, and other assistance all to the extent deemed necessary or desirable by said Assignee (a) for perfecting in said Assignee the right, title and interest herein conveyed; (b) for complying with any duty of disclosure; (c) for prosecuting any of said applications; (d) for filing and prosecuting substitute, divisional, continuing or additional applications covering said invention; (e) for filing and prosecuting applications for reissue of any of said patents; (f) for interference or other priority proceedings involving said invention; and (g) for legal proceedings involving said invention and any applications therefor and any patents granted thereon, including without limitation opposition proceedings, cancellation proceedings, priority contests, public use proceedings, reexamination proceedings, compulsory licensing proceedings, infringement actions and court actions; provided, however, that the expense incurred by said Inventors in providing such cooperation shall be paid for by said Assignee.

3. The terms and covenants of this Assignment shall inure to the benefit of said Assignee, its successors, assigns and other legal representatives, and shall be binding upon said Inventors, their respective heirs, legal representatives and assigns.

4. Said Inventors hereby jointly and severally warrant and represent that they have not entered and will not enter into any assignment, contract, or understanding in conflict herewith.

Date: 4/28 06 (1) Chin-Tien Chiu

Chin-Tien Chiu

Date: 4-27-06

(2) Hem Takiar

Date: 2006. 4. 28

(3)
Hui Liu

Date: Apr 28th. 2006 (4) Java Zhu

Java Zhu

Date: 4/28/06

(5) Jack Chang Chien
Jack Chang-Chien

Date: April 28, 2006

(6)
Cheemen Yu